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wherein a conductive adhesive layer is provided on said coating and said conductive adhesive layer contains a conductive filler consisting of gold, silver, platinum, nickel, zinc, palladium, or an alloy or a mixture containing these metals.

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4. (Amended) The electronic part as set forth in claim 1, wherein the thickness of said coating is less than the particle diameter of said conductive filler.

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(Twice Amended) An electronic part mounting element comprising:
an external electrode;

a coating of a conductive adhesive containing a conductive filler formed on the entire surface of the external electrode of the electronic part,

wherein said external electrode of said electronic part is electrically connected to a connecting terminal of an element on which said electronic part is to be mounted, said coating operative as a connecting element for connecting said external electrode to said connecting terminal,

wherein said conductive filler consists of gold, silver, platinum, nickel, zinc, palladium, or an alloy or a mixture containing these metals.

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- 19. (Amended) The electronic part as set forth in claim 1, wherein the surface roughness (Ra) of said external electrode of is in the range of 0.1 μ m to 10.0 μ m.
- 20. (Amended) The electronic part mounting element as set forth in claim 6, wherein the surface roughness (Ra) of said external electrode of is in the range of 0.1

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 μ m to 10.0 μ m.

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- 21. (Amended) The electronic part mounting element as set forth in claim 9, wherein the surface roughness (Ra) of said external electrode of is in the range of 0.1 μ m to 10.0 μ m.
- 22. (Amended) The electronic part as set forth in claim 18, wherein the surface roughness (Ra) of said external electrode of is in the range of 0.1 μ m to 10.0 μ m.
- 23. (Amended) The electronic part as set forth in claim 1, wherein the surface roughness (Ra) of said external electrode of is in the range of 0.1 μ m to 5.0 μ m.
- 24. (Amended) The electronic part mounting element as set forth in claim 6, wherein the surface roughness (Ra) of said external electrode of is in the range of 0.1 μm to 5.0 μm .
- 25. (Amended) The electronic part mounting element as set forth in claim 9, wherein the surface roughness (Ra) of said external electrode of is in the range of 0.1 μ m to 5.0 μ m.
- 26. (Amended) The electronic part as set forth in claim 18, wherein the surface roughness (Ra) of said external electrode of is in the range of 0.1 μ m to 5.0 μ m.